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CHECKED IN

Date:	22-08-2018
Program & PCB Name:	NanoPower BP8
Part Number:	100386
Revision:	4
PCB Designer:	Mogens Groth Nicolaisen
PCB Specifications:	
Base Specification:	IPC-6012/6013-D class 2+ (Class 3 regarding requirements for Annular ring breakout, Surface and copper plating, and Copper wrap plating)
Material:	Glass/polyimide (GI) IPC-4101/40 Arlon 85N or Arlon 35N
Construction:	High Density Interconnect (1+n+1)
Layer count:	8
Stackup detailes:	See Stack-up sheet
Tolerances:	Thickness: +/- 10%, Outline: +/- 10%, Cluster dimensions: +/- 10%

Special requirements:		
☑	Notation Top	White low-outgassing epoxy
☑	Notation Bottom	White low-outgassing epoxy
☐	Nickel/Hard Gold edge plating:	See Gold plated mechanical layer in files included below.
☐	Vias in pad has to be filled and capped	All drilled vias
☑	All Microvia has to be with copper filling.	Unless otherwise agreed
☑	Surface finish:	Hot Oil reflow SnPb - unless otherwise agreed
☐	Nickel/Hard gold contacts:	See Gold plated mechanical layer in files included below.
☑	Panelization	Use Gomspace standard cluster template - Choose Cluster 1 or Cluster 2
☑	Minimum isolation distance:	150um
☐	Countersunk holes	All 2.5 mm holes countersunk by 90 degrees to 5.5mm opening from the buttom layer.
☐	PCB manufacturer logo - **Not allowed**	unless otherwise agreed
☑	PCB Manufacturer serial number	See specified area in mechanical layer 7
☑	Stencil data required	Stencil data shall be based on compensated production files
☑	Electrically test to be done.	In accordance with IPC-9552, test level B
☐	Peelable Solder Mask:	
☐	Impedance controlled nets	
☑	Tolerances	Thickness: +/- 10%, Outline: +/- 10%, Cluster dimensions: +/- 10%

Files included in data package

	File Description	File Name	Format	Comments
☑	Read-Me File	ReadMe.pdf	ACROBAT	This Document
☑	Outline (Mechanical 4)	BP8_default_no_flipflop.GM4	OBD++	Board Outline
☑	CID+LOGO (Mechanical 6)	BP8_default_no_flipflop.GM6	ODB++	Notation Top - white low-outgassing epoxy
☑	Top Paste	BP8_default_no_flipflop.GTP	OBD++	Top Paste
☑	Top Side Components	BP8_default_no_flipflop.GTL	ODB++	L1 in stackup
☑	Signal Layer 1	BP8_default_no_flipflop.G1	OBD++	L2 in stackup
☑	Power Layer 1	BP8_default_no_flipflop.G2	ODB++	L3 in stackup
☑	Signal Layer 2	BP8_default_no_flipflop.G3	OBD++	L4 in stackup - Flex layer
☑	Signal Layer 3	BP8_default_no_flipflop.G4	ODB++	L5 in stackup -Flex layer
☑	Power Layer 2	BP8_default_no_flipflop.G5	OBD++	L6 in stackup
☑	Signal Layer 4	BP8_default_no_flipflop.G6	ODB++	L7 in stackup
☑	Bottom Side Components	BP8_default_no_flipflop.GBL	OBD++	L8 in stackup
☑	Bottom Paste	BP8_default_no_flipflop.GBP	OBD++	Bottom Paste
☑	ODB++	BP8_default_no_flipflop.zip	ODB	Netlist etc.
☑	Stackup details	Stack-up.pdf	ACROBAT	
☑	ID-text (Mechanical 7)	BP8_default_no_flipflop.GM7	ODB++	Manufacturer serial no. notation Bottom - white low-outgassing epoxy
☐				
☐				
☐				

All files are in millimeters and showed from top view.
Format: 4:3
Any changes/production optimizations shall be approved by GomSpace.